

CAT24C208

8K (1K x 8) -Bit Dual Port Serial EEPROM for VESA Plug and Play Applications in LCD Projectors and Monitors



FEATURES

- 400 kHz I²C bus compatible*
- Complies with VESA E-EDID, E-DDC, DI-EXT and M1 specifications
- 3V to 5.5V volt operation
- Low power CMOS technology
- 16-byte page write buffer
- Self-timed write cycle with auto-clear

- 1,000,000 program/erase cycles
- 100 year data retention
- 8-pin DIP, SOIC, TSSOP or MSOP packages- Green package option
- Industrial and extended temperature ranges

DESCRIPTION

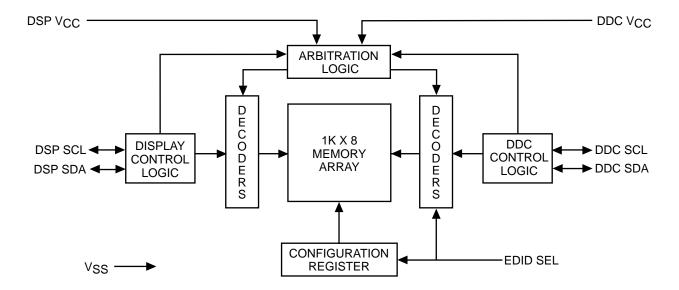
The CAT24C208 is an 8k-bit Dual Port Serial CMOS EEPROM internally organized as 1k words of 8 bits each. The CAT24C208 features a 16-byte page write buffer and can be accessed from either of two separate I²C compatible ports, DSP (SDA, SCL) and DDC (SDA, SCL) which conform to the VESA E-EDID EEPROM Standard.

Arbitration between the two interface ports is automatic and allows the appearance of individual access to the memory from each interface.

Using Catalyst's advanced CMOS technology which substantially reduces device power requirements, the CAT24C208 can be powered from either of two independent V_{CC} inputs.

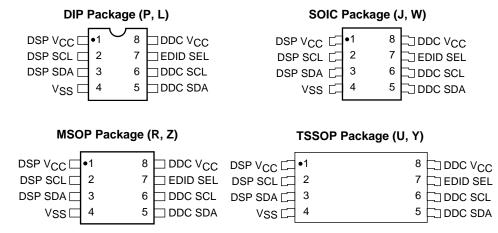
The CAT24C208 operates over the full industrial and extended temperature range and is available in miniature 8-pin DIP, SOIC, TSSOP and MSOP packages.

BLOCK DIAGRAM



^{*} Catalyst Semiconductor is licensed by Philips Corporation to carry the I²C Bus Protocol.

PIN CONFIGURATION



PIN DESCRIPTION

Pin Number	Pin Name	Function			
1	DSP V _{cc}	Device power from display controller			
2	DSP SCL	The CAT24C208 DSP serial clock bidirectional pin is used to clock all data transfers into or out of the device DSP SDA pin and is also used to block DSP Port access when DDC Port is active.			
3	DSP SDA	DSP Serial Data/Address. The bidirectional DSP serial data/address pin is used to transfer data into and out of the device from a display controller. The DSP SDA pin is an open drain output and can be wire-OR'ed with other open drain or open collector outputs.			
4	V _{ss}	Device ground.			
5	DDC SDA	DDC Serial Data/Address. The bidirectional DDC serial data/address pin is used to transfer data into and out of the device from a DDC host. The DDC SDA pin is an open drain output and can be wire-OR'ed with other open drain or open collector outputs.			
6	DDC SCL	The CAT24C208 DDC serial clock bidirectional pin is used to clock all data transfers into or out of the device DDC SDA pin, and is used to block DDC Port for access when DSP Port is active.			
7 EDID SEL		EDID select. The CAT24C208 EDID select input selects the active ban of memory to be accessed via the DDC SDA/SCL interface as set in the configuration register.			
8	DDC V _{cc}	Device power when powered from a DDC host.			

ABSOLUTE MAXIMUM RATINGS*

Temperature Under Bias55°C to +125°C
Storage Temperature65°C to +150°C
Voltage on Any Pin with Respect to Ground ⁽¹⁾ 2.0V to $+V_{CC} + 2.0V$
V _{CC} with Respect to Ground2.0V to +7.0V
Package Power Dissipation Capability (T _A = 25°C)
Lead Soldering Temperature (10 secs) 300°C
Output Short Circuit Current ⁽²⁾ 100mA

*COMMENT

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions outside of those listed in the operational sections of this specification is not implied. Exposure to any absolute maximum rating for extended periods may affect device performance and reliability.

Reliability Characteristics

Symbol	Parameter	Reference Test Method	Min	Тур	Max	Units
N _{END} (3)	Endurance	MIL-STD-883, Test Method 1033	1,000,000			Cycles/Byte
T _{DR} ⁽³⁾	Data Retention	MIL-STD-883, Test Method 1008	100			Years
V _{ZAP} ⁽³⁾	ESD Susceptibility	MIL-STD-883, Test Method 3015	4000			Volts
I _{LTH} (3)(4)	Latch-up	JEDEC Standard 17	100			mA

D.C. OPERATING CHARACTERISTICS

V_{CC} = 3V to 5.5V, unless otherwise specified.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
I _{cc}	Power Supply Current	f _{SCL} = 100 KHz			3	mA
I _{SB}	Standby Current (V _{CC} = 5.0V)	V_{IN} = GND or either DSP or DDC V_{CC}			50	μΑ
I _{LI}	Input Leakage Current	V_{IN} = GND to either DSP or DDC V_{CC}			10	μΑ
I _{LO}	Output Leakage Current	$V_{OUT} = GND$ to either DSP or DDC V_{CC}			10	μΑ
V _{IL}	Input Low Voltage		- 1		V _{cc} x 0.3	V
V _{IH}	Input High Voltage		V _{cc} x 0.7		V _{cc} + 0.5	V
VHYS	Input Hysteresis		0.05			V
V _{OL1}	Output Low Voltage (V _{CC} = 3V)	I _{OL} = 3 mA			0.4	V
V _{CCL1}	Leakage DSP $V_{\rm cc}$ to DDC $V_{\rm cc}$				<u>+</u> 100	μΑ
V _{CCL2}	Leakage DDC $\rm V_{\rm cc}$ to DSP $\rm V_{\rm cc}$				<u>+</u> 100	μΑ

Note:

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⁽¹⁾ The minimum DC input voltage is -0.5V. During transitions, inputs may undershoot to -2.0V for periods of less than 20 ns. Maximum DC voltage on output pins is V_{CC} +0.5V, which may overshoot to V_{CC} + 2.0V for periods of less than 20ns.

⁽²⁾ Output shorted for no more than one second. No more than one output shorted at a time.

⁽³⁾ This parameter is tested initially and after a design or process change that affects the parameter.

⁽⁴⁾ Latch-up protection is provided for stresses up to 100 mA on address and data pins from -1V to V_{CC} +1V.

CAPACITANCE $T_A = 25^{\circ}C$, f = 1.0 MHz, $V_{CC} = 5V$

Symbol	Parameter	Conditions	Min	Тур	Max	Units
C _{I/O} ⁽¹⁾	Input/Output Capacitance (Either DSP or DDC SDA)	$V_{I/O} = 0V$			8	pF
C _{IN} ⁽¹⁾	Input Capacitance (EDID, Either DSP or DDC SCL)	V _{IN} = 0V	·		6	pF

Note:

(1) This parameter is tested initially and after a design or process change that affects the parameter.

A.C. CHARACTERISTICS

 V_{CC} = 3V to 5.5V, unless otherwise specified.

Read & Write Cycle Limits

Symbol	Parameter	Min	Max	Units
F _{SCL}	Clock Frequency		400	kHz
T _I ⁽¹⁾	Noise Suppression Time Constant at SCL, SDA Inputs		100	ns
t _{AA}	SCL Low to SDA Data Out and ACK Out		1	μs
t _{BUF} ⁽¹⁾	Time the Bus Must be Free Before a New Transmission Can Start	1.2		μs
t _{HD:STA}	Start Condition Hold Time	0.6		μs
t _{LOW}	Clock Low Period	1.2		μs
t _{HIGH}	Clock High Period	0.6		μs
t _{SU:STA}	Start Condition Setup Time (for a Repeated Start Condition)	0.6		μs
t _{HD:DAT}	Data In Hold Time	0		ns
t _{SU:DAT}	Data In Setup Time	50		ns
t _R ⁽¹⁾	SDA and SCL Rise Time		0.3	μs
t _F ⁽¹⁾	SDA and SCL Fall Time		300	ns
t _{su:sto}	Stop Condition Setup Time	0.6		μs
t _{DH}	Data Out Hold Time	100		ns

Note:

Power-Up Timing(1)(2)

Symbol	Symbol Parameter tpur Power-up to Read Operation		Тур	Max	Units
tpur	Power-up to Read Operation			1	ms
t _{PUW}	Power-up to Write Operation			1	ms

Write Cycle Limits

Symbol	Symbol Parameter		Тур	Max	Units
t _{WR}	Write Cycle Time			5	ms

The write cycle time is the time from a valid stop condition of a write sequence to the end of the internal program/erase cycle. During the write cycle, the bus interface circuits are disabled, SDA is allowed to remain high, and the device does not respond to its slave address.

⁽¹⁾ This parameter is tested initially and after a design or process change that affects the parameter.

⁽²⁾ tpuR and tpuW are the delays required from the time V_{CC} is stable until the specified operation can be initiated.

FUNCTIONAL DESCRIPTION

The CAT24C208 has a total memory space of 1K bytes which is accessible from either of two I²C interface ports, (DSP_SDA and DSP_SCL) or (DDC_SDA and DDC_SCL), and with the use of segment pointer at address 60h. On power up and after any instruction, the segment pointer will be in segment 00h for DSP and in segment 00h of the bank selected by the configuration register for DDC.

The entire memory appears as contiguous memory space from the perspective of the display interface (DSP_SDA and DSP_SCL), see Table 2, and Figures 11 to Figure 18 for a complete description of the DSP Interface.

A configuration register at addresses 62/63h is used to configure the operation and memory map of the device as seen from the DDC interface, (DDC_SDA and DDC_SCL).

Read and write operations can be performed on any location within the memory space from the display DSP interface regardless of the state of the EDID SEL pin or the activity on the DDC interface. From the DDC

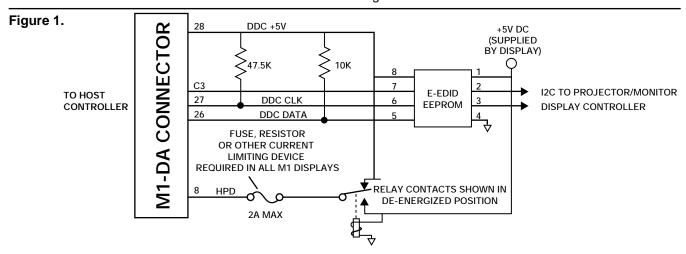
interface, the memory space appears as two 500 byte banks of memory, with 2 segments each 00h and 01h in the upper and lower bank, see Table 1.

Each bank of memory can be used to store an E-EDID data structure. However, only one bank can be read through the DDC port at a time. The active bank of memory (that is, the bank that appears at address A0h on the DDC port) is controlled through the configuration register at 62/63h and the EDID_SEL pin.

No write operations are possible from the DDC interface unless the DDC Write Enable bit is set (WE = 1) in the device configuration register at device address 62h.

The device automatically arbitrates between the two interfaces to allow the appearance of individual access to the memory from each interface.

In a typical E-EDID application the EDID_SEL pin is usually connected to the "Analog Cable Detect" pin of a VESA M1 compliant, dual-mode (analog and digital) display. In this manner, the E-EDID appearing at address A0h on the DDC port will be either the analog or digital E-EDID, depending on the state of the "Analog Cable Detect" pin (pin C3 of the M1-DA connector). See Figure 1.



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Table 1: DDC Interface

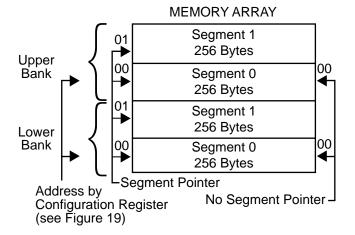
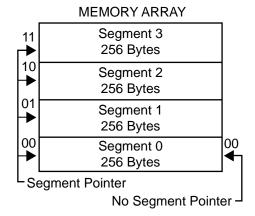


Table 2: DSP Interface



I²C Bus Protocol

The following defines the features of the I²C bus protocol:

- Data transfer may be initiated only when the bus is not busy.
- (2) During a data transfer, the data line must remain stable whenever the clock line is high. Any changes in the data line while the clock line is high will be interpreted as a START or STOP condition.

START Condition

The START Condition precedes all commands to the device, and is defined as a HIGH to LOW transition of either SDA when the respective SCL is HIGH. The CAT24C208 monitors the SDA and SCL lines and will not respond until this condition is met.

STOP Condition

A LOW to HIGH transition of SDA when SCL is HIGH determines the STOP condition. All operations must end with a STOP condition.

Acknowledge

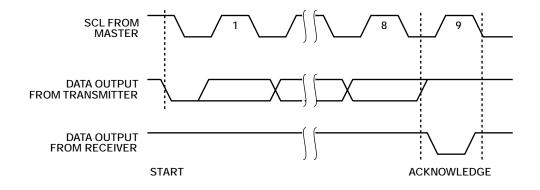
After a successful data transfer, each receiving device is required to generate an acknowledge. The acknowledging device pulls down the respective SDA line during the ninth clock cycle, signaling that it received the 8 bits of data.

The CAT24C208 responds with an acknowledge after receiving a START condition and its slave address. If the device has been selected along with a write operation, it responds with an acknowledge after receiving each 8-bit byte.

When the CAT24C208 is in a READ mode it transmits 8 bits of data, releases the respective SDA line, and monitors the line for an acknowledge. Once it receives this acknowledge, the CAT24C208 will continue to transmit data. If no acknowledge is sent by the Master, the device terminates data transmission and waits for a STOP condition.

After an unsuccessful data transfer an acknowledge will not be issued (NACK) by the slave (CAT24C208), and the master should abort the sequence. If continued the device will read from or write to the wrong address in the two instruction format with the segment pointers.

Figure 2. Acknowledge Timing



DEVICE ADDRESSING

DDC Interface

Both the DDC and DSP interfaces to the device are based on the I²C bus serial interface. All memory space operations are done at the A0/A1 DDC address pair. As such, all write operations to the memory space are done at DDC address A0h and all read operations of the memory space are done at DDC address A1h.

Figure 3 shows the bit sequence of a random read from anywhere within the memory space. The word offset determines which of the 256 bytes within segment 00h is being read. Here the segment 00h can be at the lower or upper bank depending on the configuration register.

Sequential reads can be done in much the same manner by reading successive bytes after each acknowledge without generating a stop condition. See Figure 4. The device automatically increments the word offset value (8-bit value) and with wraparound in the same segment 00h to read maximum of 256 bytes.

Figure 3. Random Access Read (Segment 00h only)

WORD OFFSET

START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	START	1010 0001	ACK	DATA	NOACK	STOP

Figure 4. Sequential Read (Segment 00h only)

WORD OFFSET

START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	START	1010 0001	ACK	DATA0	ACK	 DATAN	NOACK	STOP

Figures 5 and 6 show the byte and page write respectively. The configuration register must have the WE bit set to 1 prior to any write on DDC Port. Only the segment 00h can be accessed of either lower or upper bank.

Figure 5. Byte Write (Segment 00h only)

WORD OFFSET

START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	DATA	ACK	STOP		

Figure 6. Page Write (Segment 00h only)

WORD OFFSET

START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	DATA0	ACK	 DATA15	ACK	STOP

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The segment pointer is at the address 60h and is write-only. This means that a memory access at 61h will give undefined results. The segment pointer is a volatile register. The device configuration register at 62/63 (hex) is a non-volatile register. The configuration register will be shipped in the erased (set to FFh) state.

The segment pointer is used to expand the available DDC address space while maintaining backward compatibility with older DDC interfaces such as DDC2B. For each value of the 8-bit segment pointer one segment (256 bytes) is available at the A0/A1 pair. The standard DDC 8-bit address is sufficient to address each of the 256 bytes within a segment. Note that if the segment pointer is set to 00h then the device will behave like a standard DDC2B EEPROM.

Read and write with segment pointer can expand the addressable memory to 512 bytes in each bank with wraparound to the next segment in the same bank only. The two banks can be individually selected by the configuration register and EDID Sel pin, as shown in figure 19. The segments are selected by the two bits $S_1S_0 = 00$ or 01 in the segment address.

Figures 7 to 10 show the random read, sequential read, byte write and page write.

Figure 7. Random Access Read

START	0110 0000	ACK	xxxx xxS ₁ S ₀ Segment ADDRESS	ACK						
START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	START	1010 0001	ACK	DATA	NOACK	STOP

Figure 8. Sequential Read

START	0110 0000	ACK	xxxx xxS ₁ S ₀ Segment ADD	RESS	ACK							
START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	START	1010 0001	ACK	DATA0	ACK	 DATAN	NOACK	STOP

Figure 9. Byte Write

START	0110 0000	ACK	xxxx xxS ₁ S ₀ Segment ADD	RESS	ACK		
START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	DATA	ACK	STOP

Figure 10. Page Write

START	0110 0000	ACK	xxxx xxS ₁ S ₀ Segment ADDRESS		ACK				
START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	DATA0	ACK	 DATA15	ACK	STOP

DSP Interface

The DSP interface is similar to I²C bus serial interface. Without the segment pointer, the maximum accessible memory space is 256 bytes of segment 00h only. In the sequential mode the wrap around will be in the same segment also. Figures 11 to 14 show the read and write on the DSP Port.

Figure 11. Random Access Read

Figure 12. Sequential Read

	START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	START	1010 0001	ACK	DATA0	ACK	 DATAN	NOACK	STOP
- 1								1					

Figure 13. Byte Write

Figure 14. Page Write

START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	DATA0	ACK		DATA15	ACK	STOP	
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The segment pointer is used to expand the available DSP port addressable memory to 1k bytes, divided into four segments of 256 bytes each. The four segments are selected by two bits $S_1S_0 = 00$, 01, 10, 11 in the segment address. Figures 15 to 18 show the random read, sequential read, byte write and page write.

Figure 15. Random Access Read

START	0110 0000	ACK	xxxx xxS ₁ S ₀ Segment ADDRESS		ACK					
START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	START	1010 0001	ACK	DATA	NOACK	STOP

Figure 16. Sequential Read

ST	ART	0110 0000	ACK	xxxx xxS ₁ S ₀ Segm	xxxx xxS ₁ S ₀ Segment ADDRESS		ACK						
ST	ART	1010 0000	ACK	A7 - A0 ADDRESS	ACK	START	1010 0001	ACK	DATA0	ACK	 DATAN	NOACK	STOP

Figure 17. Byte Write

START	0110 0000	ACK	xxxx xxS ₁ S ₀ Segment ADD	RESS	ACK		
START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	DATA	ACK	STOP

Figure 18. Page Write

START	0110 0000	ACK	xxxx xxS ₁ S ₀ Segr	xxxx xxS ₁ S ₀ Segment ADDRESS						
START	1010 0000	ACK	A7 - A0 ADDRESS	ACK	DATA0	ACK		DATA15	ACK	STOP

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ARBITRATION

The device performs a simplistic arbitration between the DDC and display interfaces. While the arbitration scheme described is not foolproof, it does prevent most errors. The arbitration logic uses "clock stretching", an I²C bus term, to hold off writes from one port while the other port is active.

Arbitration logic within the device monitors activity on DDC_SCL and DSP_SCL. When both I2C ports are idle, DDC_SCL and DSP_SCL are both high and the arbitration logic is inactive. When either DDC_SCL or DSP_SCL is pulled low, initiating a read or write, the arbitration logic pulls down the other SCL line and holds

it low, holding off activity on the other port (by stretching the clock on that port). When the initiating SCL line has remained high for one full second, the arbitration logic assumes that the initiating devices is finished and releases the other SCL line. If the non-initiating device has been waiting for access, it can now read or write the device.

For this scheme to work properly, both the DDC and DSP devices must properly implement clock stretching as defined by the I²C specification. Additionally, it is very important that when writing to the device that the SCL line never remains high longer than 1 second, until the write is complete. This prevents the other port from having access until the device is fully written.

CONFIGURATION REGISTER

	MSB							LSB
Register Function	7	6	5	4	3	2	1	0
Configuration Register	Х	Х	Х	Х	WE	AB1	AB0	NB

Function Description:

NB: Number of memory banks in DDC port memory map. 0 = 2 Banks, 1 = 1 Bank

AB0: Active Bank Control Bit 0 (See Figure 19)
AB1: Active Bank Control Bit 1 (See Figure 19)

WE DDC: Write Enable 0 = Write Disabled, 1= Write Enabled

Note: WE affects only write operations from the DDC port, not the display port. The display port always has write access.

Figure 19. Configuration Register Truth Table

AB1	AB0	NB	EDID Select Pin	Active Bank	
0	Х	0	0	Lower Bank	
0	Х	0	1	Upper Bank	
1	0	0 X Lowe		Lower Bank	
1	1	0	Х	Upper Bank	
Х	Х	1	X Lower (only)		

The configuration register is a non-volatile register and is available from either DSP or DDC port at address 62h/63h for write and read resp.

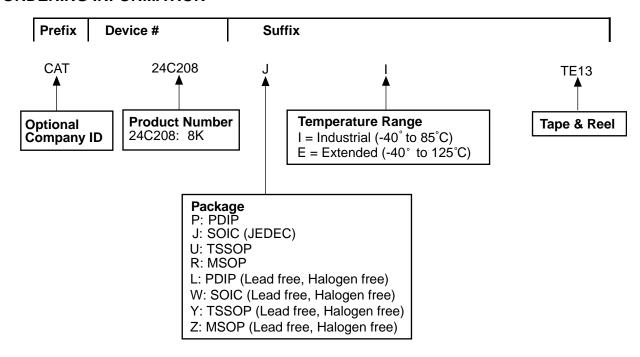
Figure 20. Read Configuration Register

	START	0110 0011	ACK	DATA	NO ACK	STOP
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Figure 21. Write Configuration Register

START	0110 0010	ACK	DUMMY ADDRESS	ACK	XXXX WE AB1 AB0 NB	ACK	STOP
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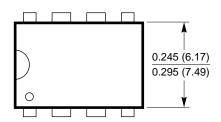
ORDERING INFORMATION

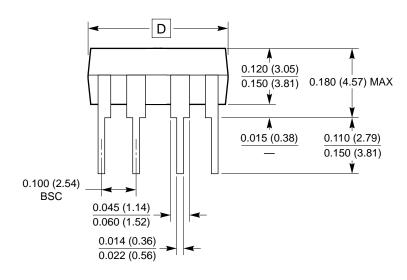


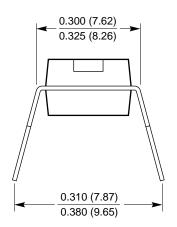
Notes:

(1) The device used in the above example is a CAT24C208JI-TE13 (SOIC, Industrial Temperature, 3 Volt to 5.5 Volt Operating Voltage, Tape & Reel)

8 Lead PDIP (P, L)

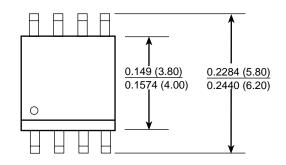


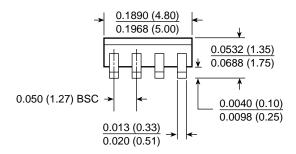


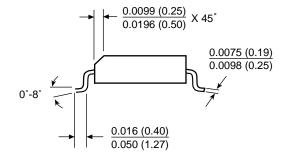


Dimension D				
Pkg	Max			
8L	0.355 (9.02)	0.400 (10.16)		

8 Lead 150 mil Wide SOIC (J, W)

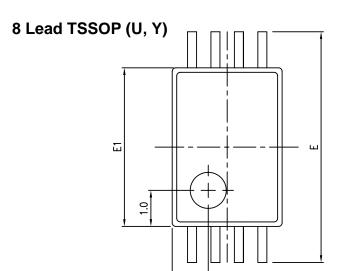


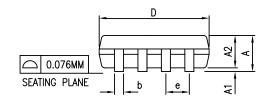




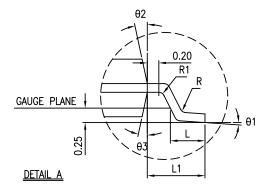
Notes:

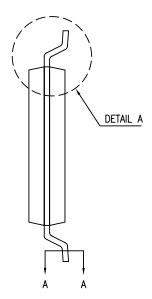
- 1. Complies with JEDEC publication 95 MS-012 dimensions; however, some dimensions may be more stringent.
- 2. All linear dimensions are in inches and parenthetically in millimeters.
- 3. Lead coplanarity is 0.004" (0.102mm) maximum.

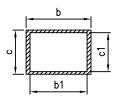




1.0







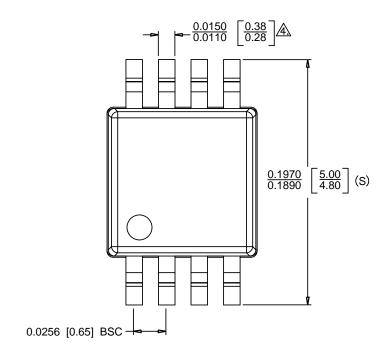
SECTION A-A

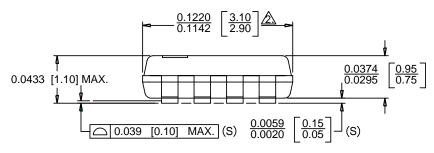
CVAIDOL	DIME	nsion ii	N MM	DIMENSION IN INCH			
SYMBOL	MIN.	NOM	MAX.	MIN.	NOM	MAX.	
Α			1.20			.043	
A1	0.05		0.15	.002		.006	
A2	0.80	0.90	1.05	.031	.035	.041	
L	0.50	0.60	0.75	.020	.024	.030	
D	2.90	3.00	3.10	.114	.118	.122	
E	6.30	6.40	6.50	.248	.252	.256	
E1	4.30	4.40	4.50	.169	.173	.177	
R	0.09			.004			
R1	0.09			.004			
b	0.19		0.30	.007		.012	
b1	0.19	0.22	0.25	.007	.009	.010	
С	0.09		0.20	.004		.008	
c1	0.09		0.16	.004		.006	
L1		1.0 REF		.039 REF.			
е	0.65 BSC.			.026 BSC.			
θ1	0		8	0		8	
θ2	12 REF.			12 REF.			
θ3	12 REF.			12 REF.			
N	8						
REF	JEDEC MO-153 VARIATION AA						

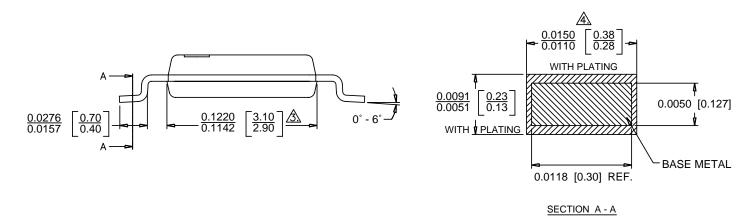
Notes:

1. Lead coplanarity is 0.004" (0.102mm) maximum.

8 Lead MSOP (R, Z)







REVISION HISTORY

Date	Rev.	Reason
2/18/2004	С	Changed volt operation to 3V to 5.5V
		Updated Block Diagram
		Updated Pin Descriptions
		Updated DC Operating Characteristics
		Updated AC Characteristics
		Changed/Added figures 3 - 21
		Updated Ordering Information
03/25/2005	D	Updated Function Description
		Updated Oedering Information

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